Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.016”**

**A**

**.016”**

**Top Material: Al**

**Backside Material:**

**Bond Pad Size: .004 X .004”**

**Backside Potential:**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .016” X .016” DATE: 11/1/21**

**MFG: ZETEX THICKNESS .000” P/N: 1N4148**

**DG 10.1.2**

#### Rev B, 7/1